

主要材料/BOM 清单信息(Information of Material/BOM list):

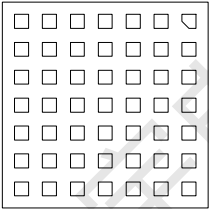
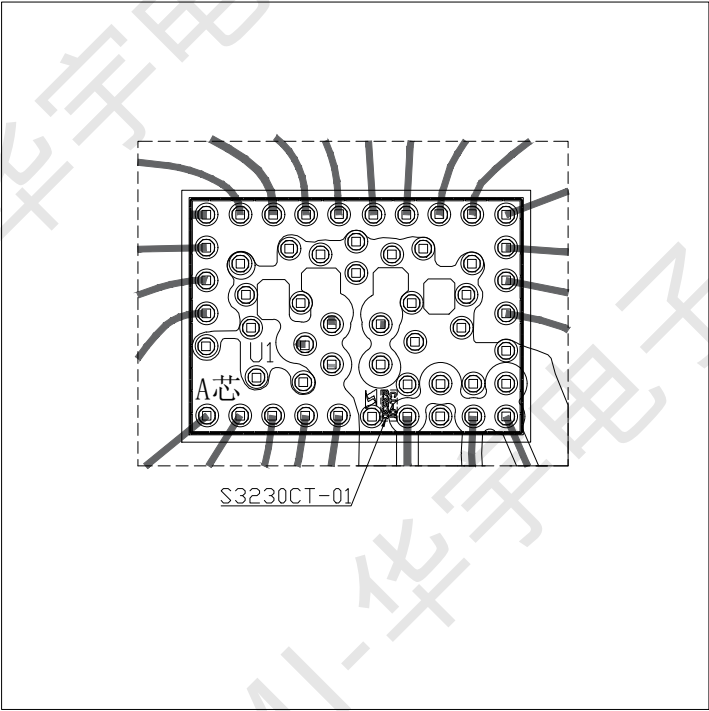
| 材料 |     |                      | 描述                                             | 备注   |
|----|-----|----------------------|------------------------------------------------|------|
| 1  | 基板  | U33011JM4M           | 240X76. 3X0. 35                                | 客供   |
| 2  | A芯  | WUM330SD7M           | 1395*990 (不包含切割道)*200um<br>(不包含bump高度)<br>(U1) | 客供   |
| 3  | 助焊剂 | TACFLUX 026S         | /                                              | 钢泰   |
| 4  | 塑封料 | G311ACCver.GR        | /                                              | 住友电木 |
| 5  | 分离膜 | TB 50 μ m*142mm TOWA | /                                              | TOWA |

|         |        |
|---------|--------|
| 塑封模具    | C模     |
| 基板切割道宽度 | 0. 2mm |

注意：客户释放量产图纸。

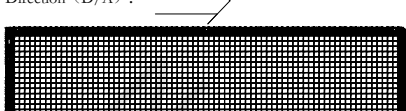
|                                                                                                                                                                                                                     |  |   |   |                      |   |                 |                                               |  |                  |                       |                               |  |
|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|--|---|---|----------------------|---|-----------------|-----------------------------------------------|--|------------------|-----------------------|-------------------------------|--|
| <div><div></div><div>池州华宇电子科技股份有限公司<br/>CHI ZHOU HISEMI ELECTRONICS TECHNOLOGY CO.,LTD</div></div> <div>焊线图纸 Bonding Diagram</div> |  |   |   | 客户代码<br>Customer No. |   | 1200            | 线图号<br>Drawing No.                            |  | HY-PX-1200-111 A |                       | 页码 Page<br>2 / 4              |  |
|                                                                                                                                                                                                                     |  |   |   | 产品名称<br>Product Type |   | STR3230-12 M3.0 |                                               |  | 封装外型<br>PKG Type |                       | FCLGA49L(2.95X2.95X0.75-P0.4) |  |
| 助焊剂<br>Flux                                                                                                                                                                                                         |  | / | / | /                    | / | /               | 塑封料型号(绿色环保)<br>Compound Type (Green)          |  |                  | 基板编码<br>Substrate No. |                               |  |
| TACFLUX 026S                                                                                                                                                                                                        |  | / | / | /                    | / | /               | 首选(Preferred): G311ACCver.GR<br>备选(Optional): |  |                  | U33011JM4M            |                               |  |
| 客户图号<br>Customer drawing NO.                                                                                                                                                                                        |  |   |   |                      |   |                 |                                               |  |                  |                       |                               |  |

PIN1



PIN1

底部示意图

|                                                                                     |  |                                                                                     |  |                            |  |
|-------------------------------------------------------------------------------------|--|-------------------------------------------------------------------------------------|--|----------------------------|--|
| 框架传送方向（装片）：<br>L/F Direction（D/A）：                                                  |  | 实物图：<br>Chip photo：                                                                 |  | 特殊说明 Special Instructions： |  |
|  |  |  |  | 客户释放量产。                    |  |
| 按单颗显示方向进料                                                                           |  |                                                                                     |  |                            |  |

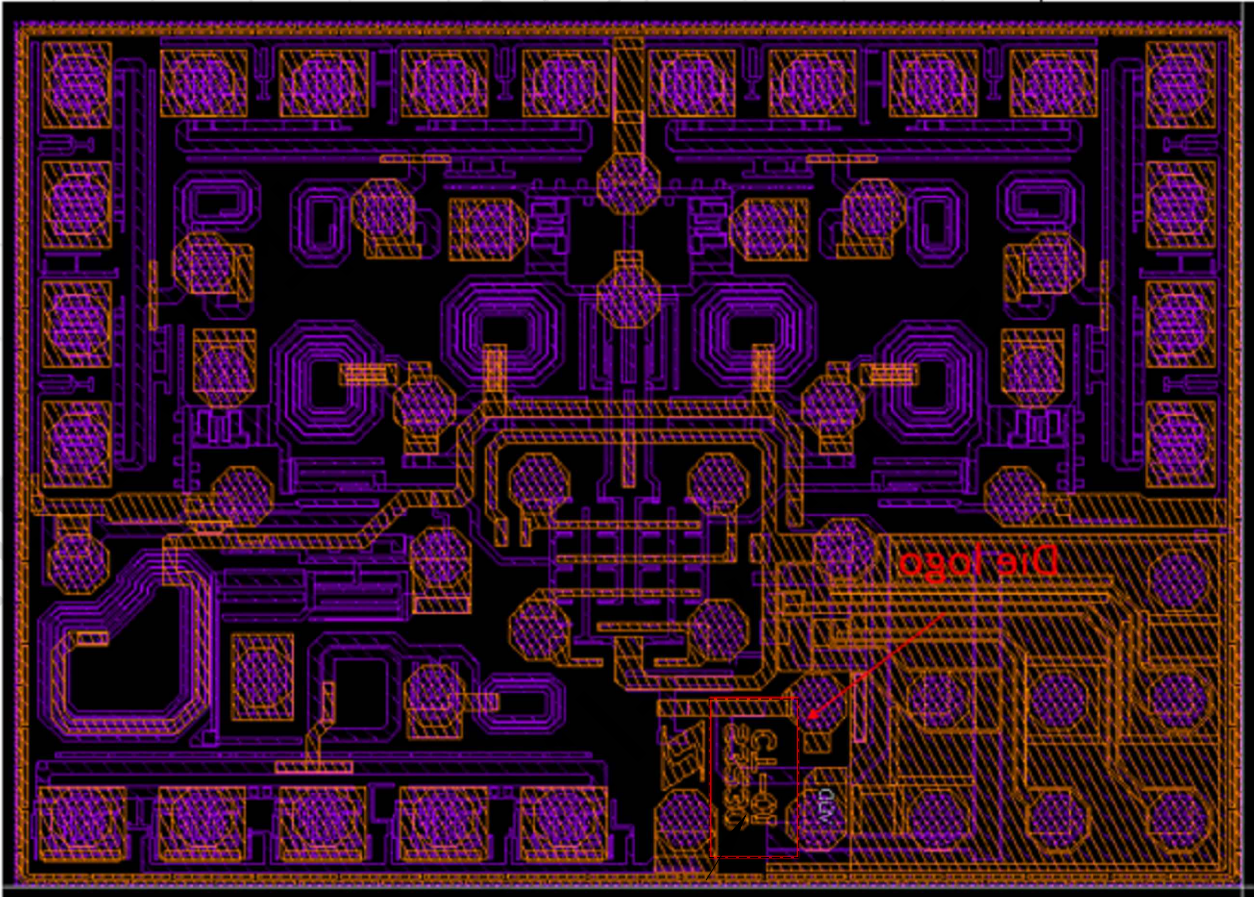
| 序号                | 芯片名称       | Die ID                              | 芯片尺寸<br>(with scribe line)          | 划片道宽度 | 晶圆尺寸 | 芯片厚度<br>UM           | 来料方式  | Wafer material*        | Bump type*         | Bump composition*                | Min bump pitch<br>(space + bump size)* UM | Min bump height* UM | Min bump diameter* UM |
|-------------------|------------|-------------------------------------|-------------------------------------|-------|------|----------------------|-------|------------------------|--------------------|----------------------------------|-------------------------------------------|---------------------|-----------------------|
| A芯<br>U1          | WUM330SD7M | S3230CT-01                          | 1457*1052(μm²)<br>57.36*41.42(mil²) | 62um  | 8    | 200um<br>(不包含bump高度) | wafer | SOI                    | copper pillar bump | 35Cu+3Ni+30SnAg                  | 133                                       | 68                  | 70                    |
| 拟制<br>Prepared by |            | 制图日期<br>Create Date                 |                                     |       |      | 2026/4/14            |       | 生效日期<br>Effective Date |                    | 客户确认签字/盖章:<br>Customer Signature |                                           |                     |                       |
| 研发审核<br>R&d check |            | 产品工程审核<br>Product engineering check |                                     |       |      |                      |       | 批准<br>Approved by      |                    |                                  |                                           |                     |                       |

\*温馨提示: 图纸为产品下线生产的唯一依据, 请您认真确认, 我司依据您回签后的图纸生产, 如图纸错误会产生不可估量损失, 谢谢!

\*warm tips: the drawing is the only basis for the production of the product. Please confirm it carefully. Our company will produce the drawings according to the drawings you have signed back, such as drawing mistakes, which will produce inestimable loss. Thank you

|                                                                                                                                                                                         |                      |                 |                    |                  |                                    |                  |
|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|----------------------|-----------------|--------------------|------------------|------------------------------------|------------------|
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|                                                                                                                                                                                         | 产品名称<br>Product Type | STR3230-12 M3.0 |                    | 封装外型<br>PKG Type | FCLGA49L (2. 95X2. 95X0. 75-P0. 4) |                  |

U1 ball map图 (TOP view)

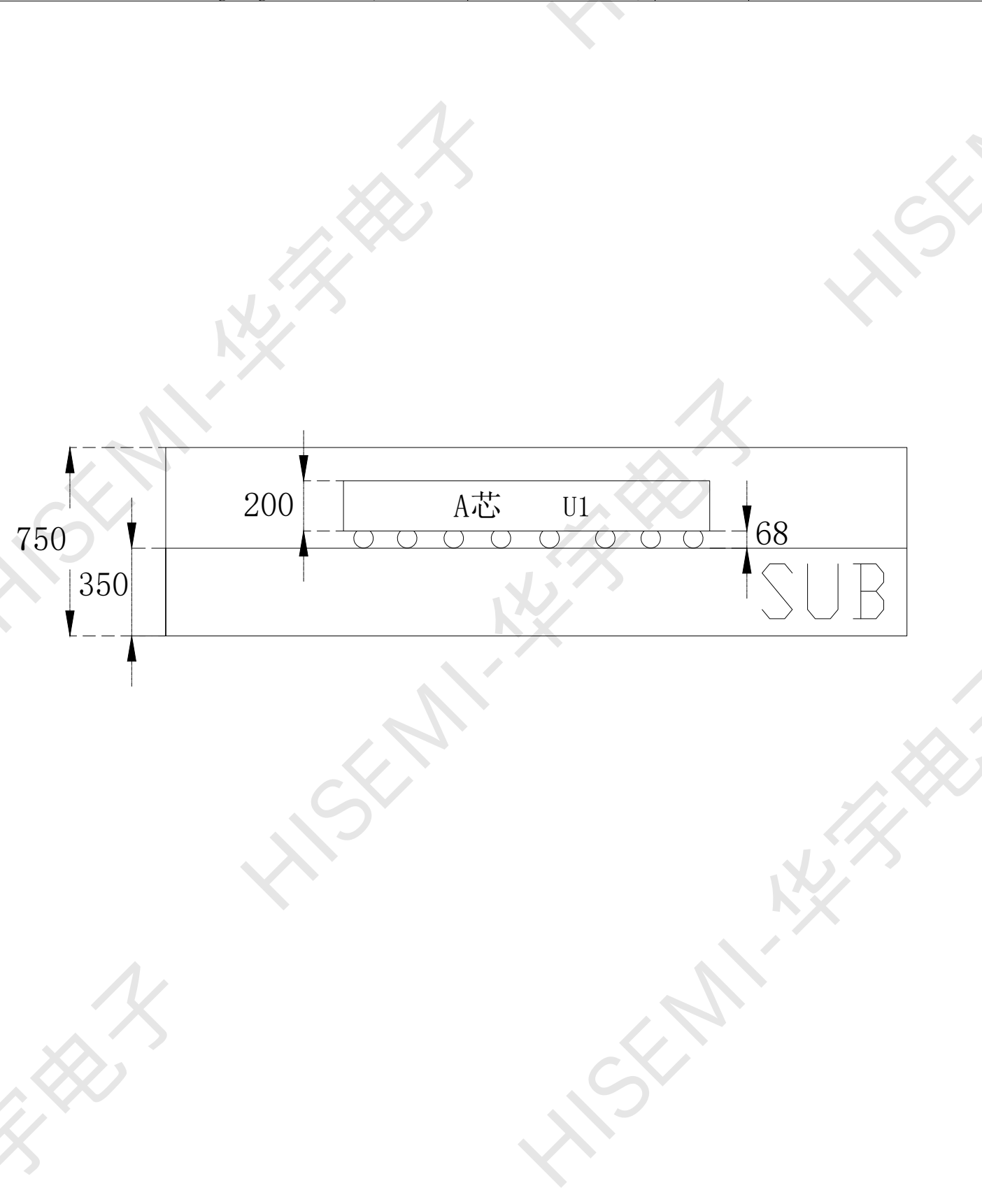


按目标区域取DIE:  
ID: S3230CT-01

|                   |                                     |           |                        |                                  |  |
|-------------------|-------------------------------------|-----------|------------------------|----------------------------------|--|
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|                                                                                                                                                                                         |                      |                 |                    |                  |                                |                  |
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